

NCE N-Channel Enhancement Mode Power MOSFET

Description

The NCE0125AK uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

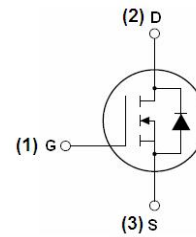
General Features

- $V_{DS} = 100V, I_D = 25A$
 $R_{DS(ON)} < 35m\Omega @ V_{GS}=10V$ (Typ:28m Ω)
 $R_{DS(ON)} < 38m\Omega @ V_{GS}=3V$ (Typ:30m Ω)
- Special process technology for high ESD capability
- High density cell design for ultra low $R_{DS(ON)}$
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation

Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

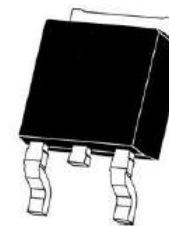
100% UIS TESTED!
100% ΔV_{DS} TESTED!



Schematic diagram



Marking and pin assignment



TO-252-2L top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE0125AK	NCE0125AK	TO-252-2L	-	-	-

Absolute Maximum Ratings ($T_c=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current-Continuous	25	A
$I_D (100^\circ\text{C})$	Drain Current-Continuous($T_C=100^\circ\text{C}$)	17.6	A
I_{DM}	Pulsed Drain Current	70	A
P_D	Maximum Power Dissipation	70	W
	Derating factor	0.5	W/ $^\circ\text{C}$
E_{AS}	Single pulse avalanche energy (Note 5)	110	mJ
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 To 175	$^\circ\text{C}$

Thermal Characteristic

$R_{\theta JC}$	Thermal Resistance, Junction-to-Case (Note 2)	2	$^\circ\text{C/W}$
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Electrical Characteristics (T_c=25°C unless otherwise noted)

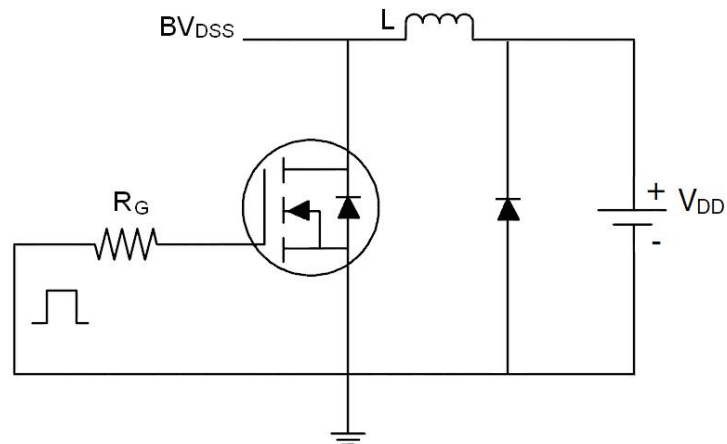
Symbol		Parameter	Condition	Min	Typ	Max	Unit
Off Characteristics							
BV _{DSS}	Drain-Source Breakdown Voltage		V _{GS} =0V I _D =250μA	100	110	-	V
I _{DSS}	Zero Gate Voltage Drain Current		V _{DS} =100V, V _{GS} =0V	-	-	1	μA
I _{GSS}	Gate-Body Leakage Current		V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)							
V _{GS(th)}	Gate Threshold Voltage		V _{DS} =V _{GS} , I _D =250μA	0.8	1.2	1.6	V
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =10V, I _D =15A	-	28	35	mΩ	
		V _{GS} =3V, I _D =15A		30	38		
g _{FS}	Forward Transconductance		V _{DS} =5V, I _D =15A	-	12	-	S
Dynamic Characteristics (Note4)							
C _{iss}	Input Capacitance		V _{DS} =50V, V _{GS} =0V, F=1.0MHz	-	3000	-	PF
C _{oss}	Output Capacitance			-	92	-	PF
C _{rss}	Reverse Transfer Capacitance			-	18.3	-	PF
Switching Characteristics (Note 4)							
t _{d(on)}	Turn-on Delay Time		V _{DD} =50V, R _L =5Ω V _{GS} =10V, R _{GEN} =3Ω	-	9	-	nS
t _r	Turn-on Rise Time			-	9	-	nS
t _{d(off)}	Turn-Off Delay Time			-	31	-	nS
t _f	Turn-Off Fall Time			-	9	-	nS
Q _g	Total Gate Charge		V _{DS} =50V, I _D =25A, V _{GS} =10V	-	70.4	-	nC
Q _{gs}	Gate-Source Charge			-	9.0	-	nC
Q _{gd}	Gate-Drain Charge			-	15.3	-	nC
Drain-Source Diode Characteristics							
V _{SD}	Diode Forward Voltage (Note 3)		V _{GS} =0V, I _S =25A	-	-	1.2	V
I _S	Diode Forward Current (Note 2)		-	-	-	25	A
t _{rr}	Reverse Recovery Time		TJ = 25°C, IF = 25A	-	34	-	nS
Q _{rr}	Reverse Recovery Charge		di/dt = 100A/μs (Note3)	-	56	-	nC

Notes:

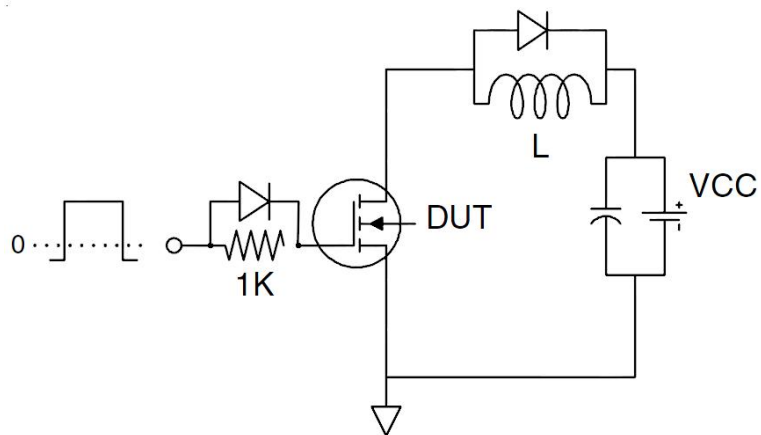
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production
5. EAS Condition : T_J=25°C, V_{DD}=50V, V_G=10V, L=0.5mH, R_g=25Ω

Test Circuit

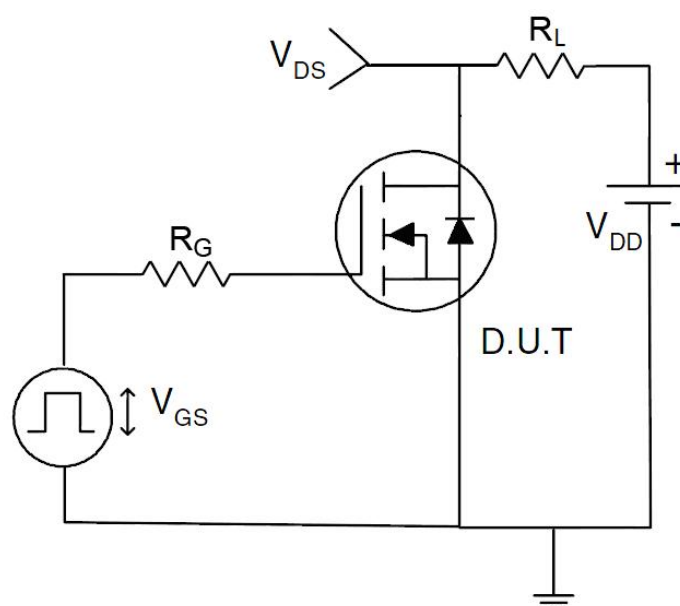
1) E_{AS} Test Circuit



2) Gate Charge Test Circuit



3) Switch Time Test Circuit



Typical Electrical and Thermal Characteristics (Curves)

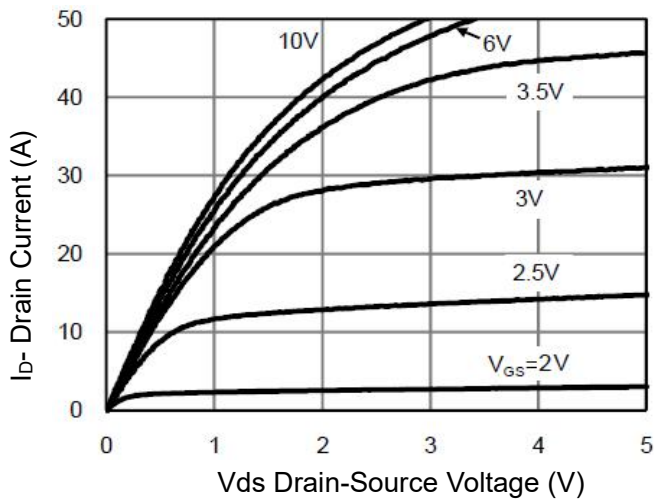


Figure 1 Output Characteristics

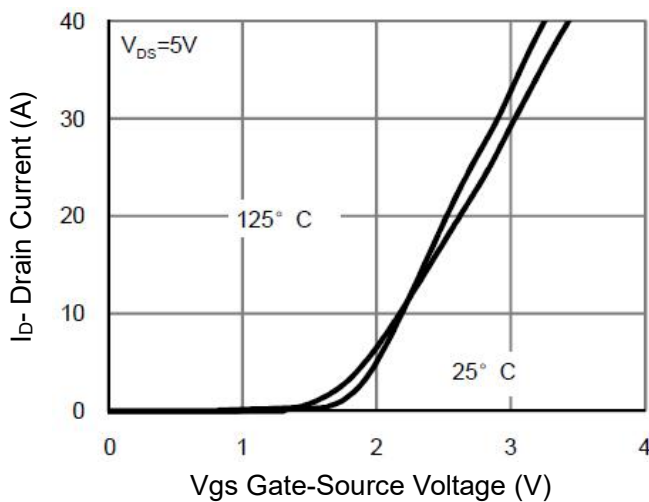


Figure 2 Transfer Characteristics

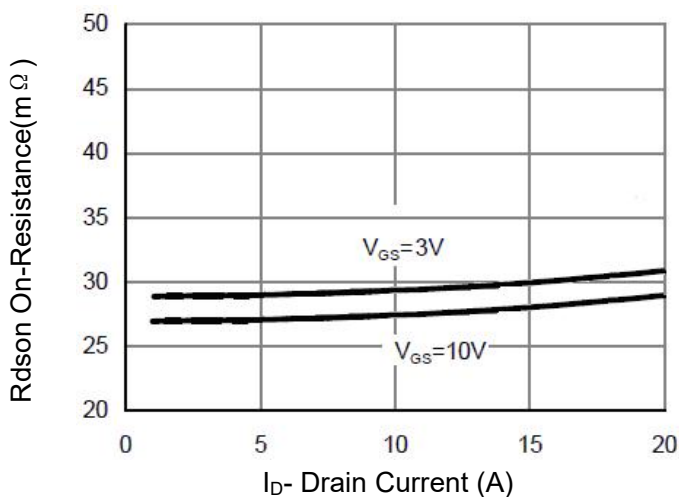


Figure 3 Rdson- Drain Current

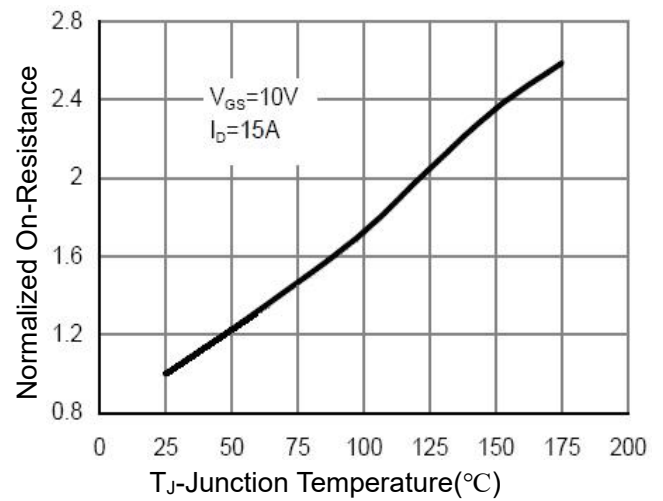


Figure 4 Rdson-Junction Temperature

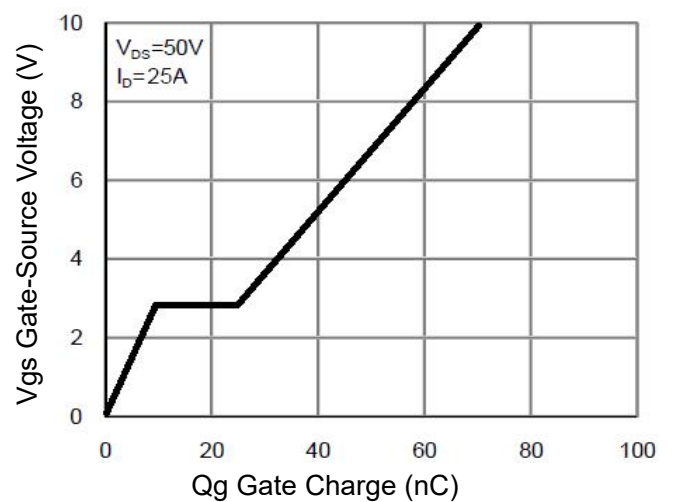


Figure 5 Gate Charge

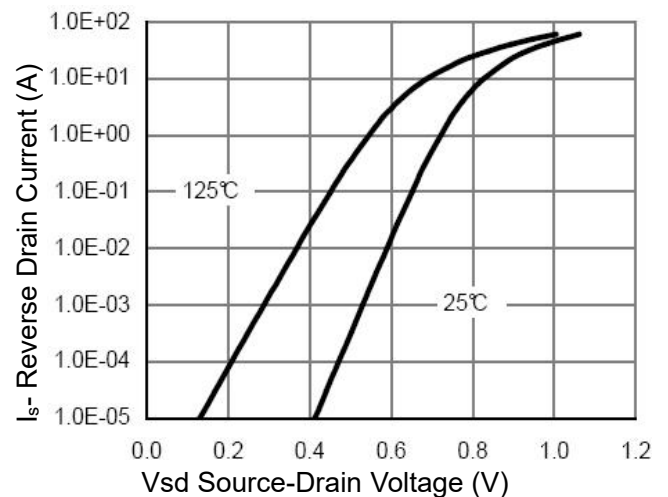


Figure 6 Source- Drain Diode Forward

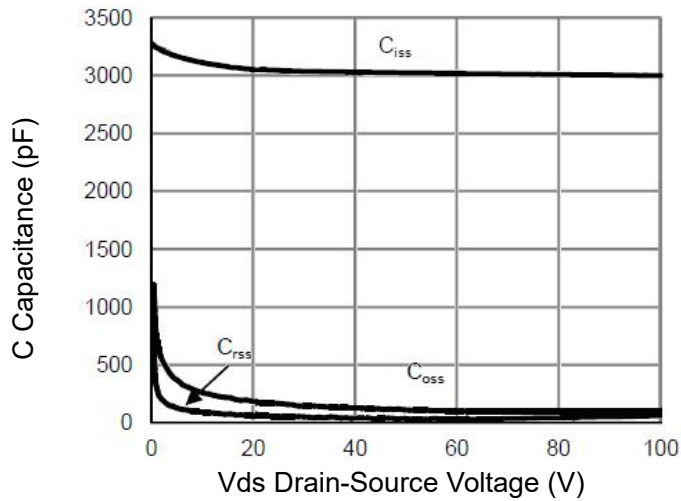


Figure 7 Capacitance vs Vds

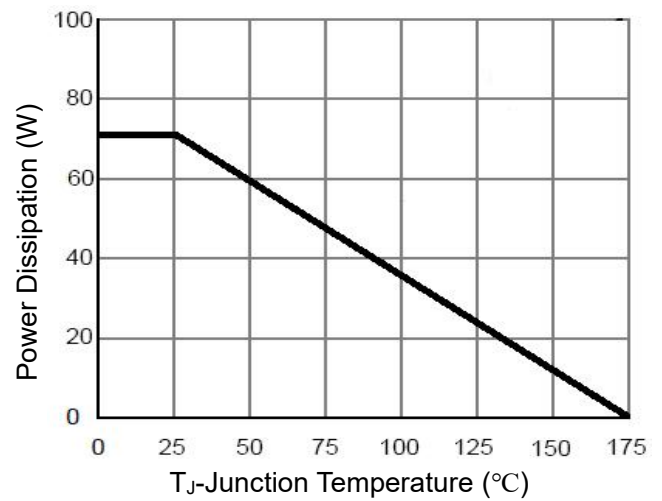


Figure 9 Power De-rating

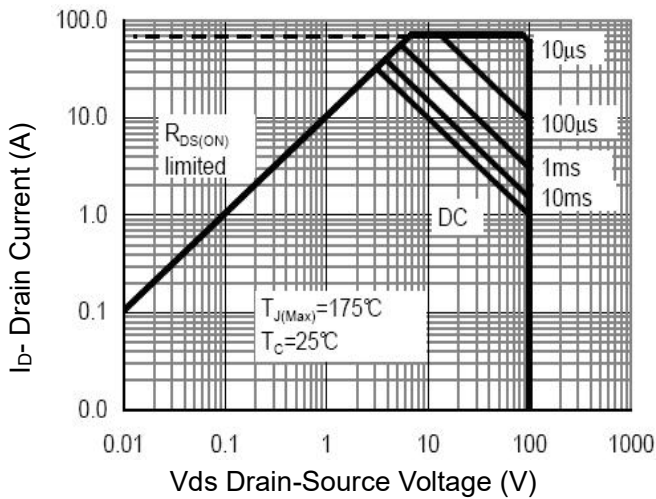


Figure 8 Safe Operation Area

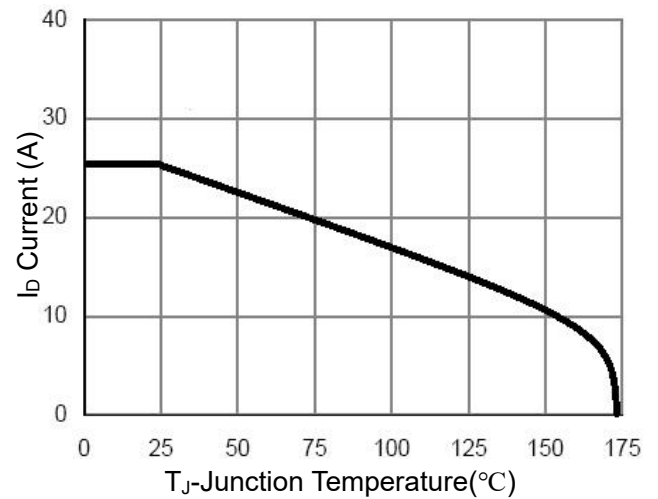


Figure 10 ID Current- Junction Temperature

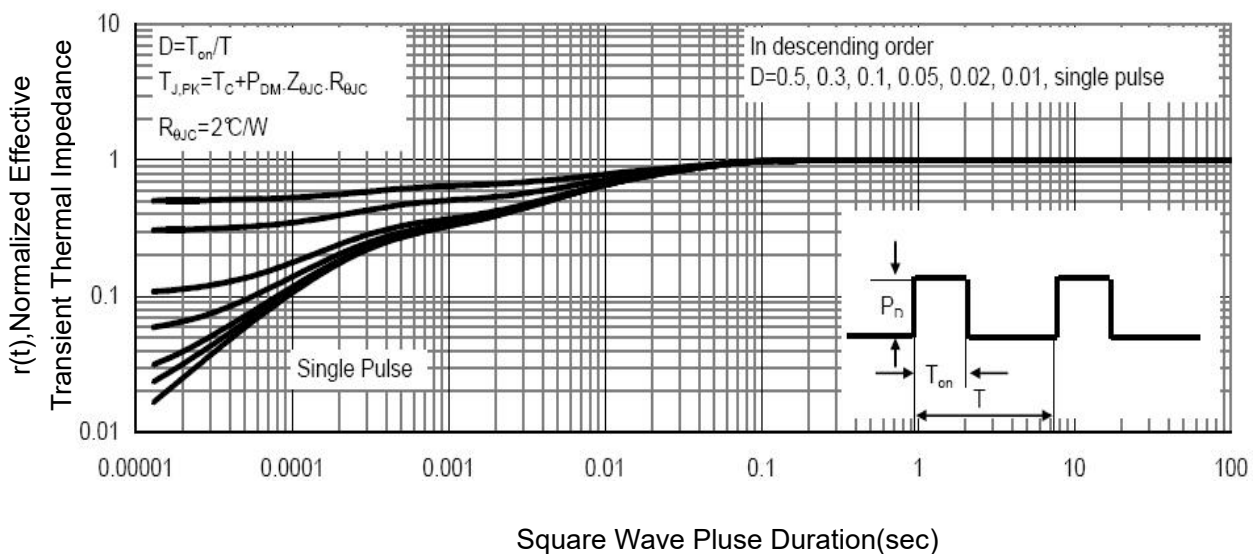
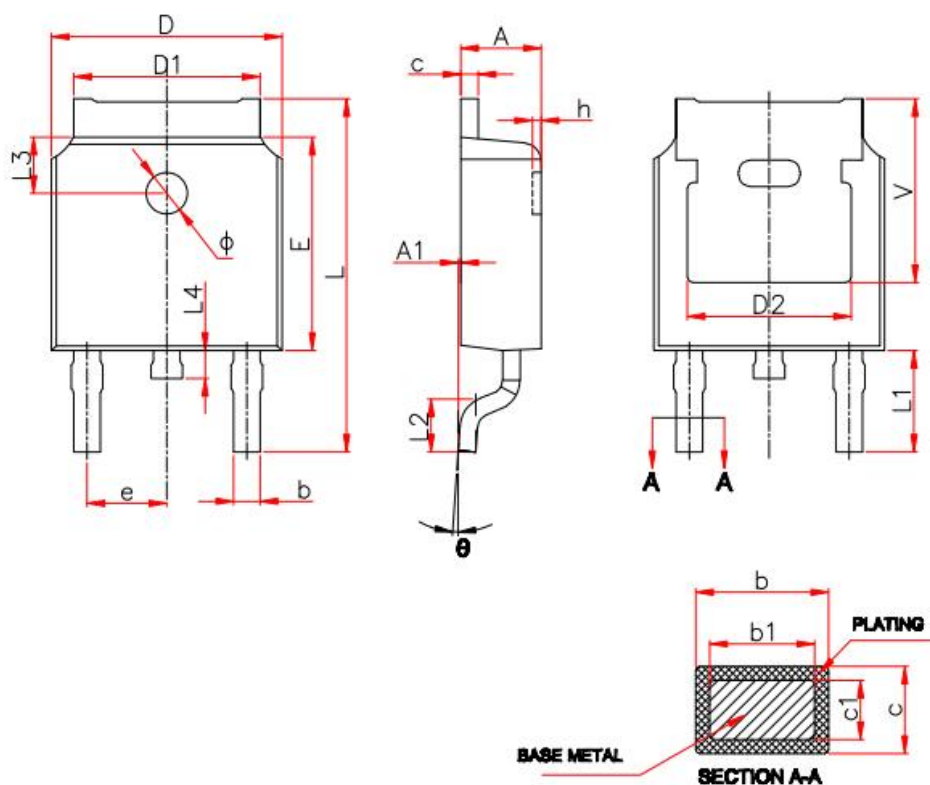


Figure 11 Normalized Maximum Transient Thermal Impedance

TO-252 Package Information



Symbol	Millimeters	
	Min.	Max.
A	2.20	2.40
A1	0.00	0.13
b	0.66	0.86
b1	0.73	0.79
c	0.46	0.58
c1	0.50	0.52
D	6.50	6.70
D1	5.10	5.46
D2	4.83 REF.	
E	6.00	6.20
e	2.19	2.39
L	9.80	10.40
L1	2.90 REF.	
L2	1.40	1.70
L3	1.60 REF.	
L4	0.60	1.00
ϕ	1.10	1.30
θ	0°	8°

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